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(54) **LEAD FRAME, ELECTRIC POWER
CONVERTING DEVICE, SEMICONDUCTOR
APPARATUS AND METHOD OF
MANUFACTURING SEMICONDUCTOR
APPARATUS**

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2924/13091 (2013.01); *H01L* 2924/181
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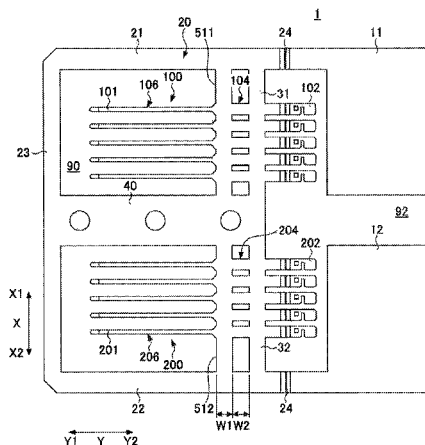
(51) **Int. Cl.**
H01L 23/495 (2006.01)
H01L 23/00 (2006.01)

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CPC ***H01L 23/49562*** (2013.01); ***H01L 23/49575***
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(57) **ABSTRACT**

According to the disclosure, a lead frame is provided, which includes: a first island and a second island that are arranged side by side; an outer peripheral frame; first leads that extend in a second direction perpendicular to the first direction; second leads that extend in the second direction; a first coupling portion that couples the first leads to the frame; a second coupling portion that couples the second leads to the frame; an intermediate portion formed between the first and second coupling portions in the first direction such that it extends in the second direction to terminate before the space between the first and second islands; and a deformation restraining portion formed or provided in at least one of the first leads, the second leads, the first and the second coupling portions and configured to restrain deformations of the first and second leads during a molding process.

8 Claims, 8 Drawing Sheets



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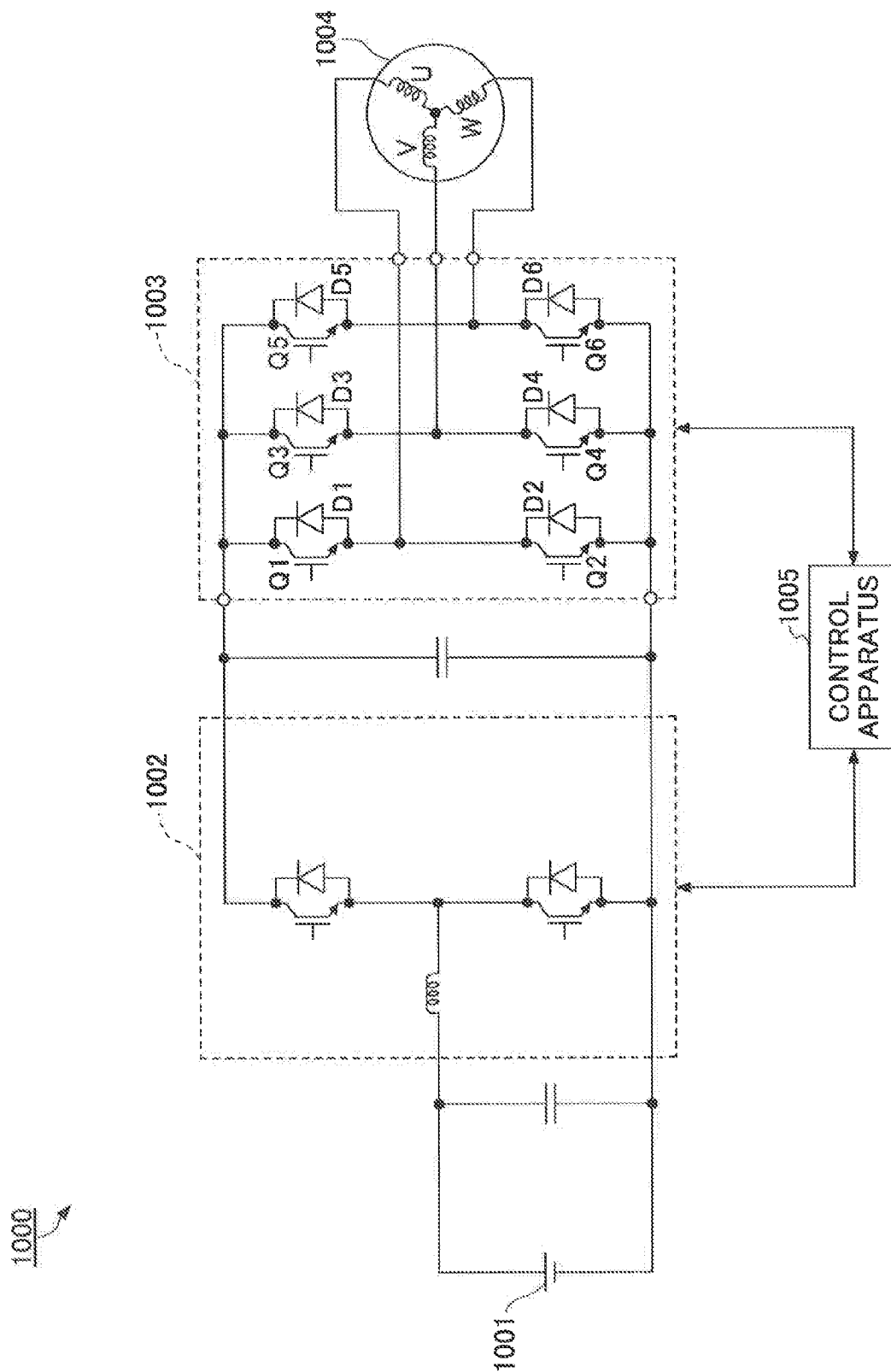


FIG. 2

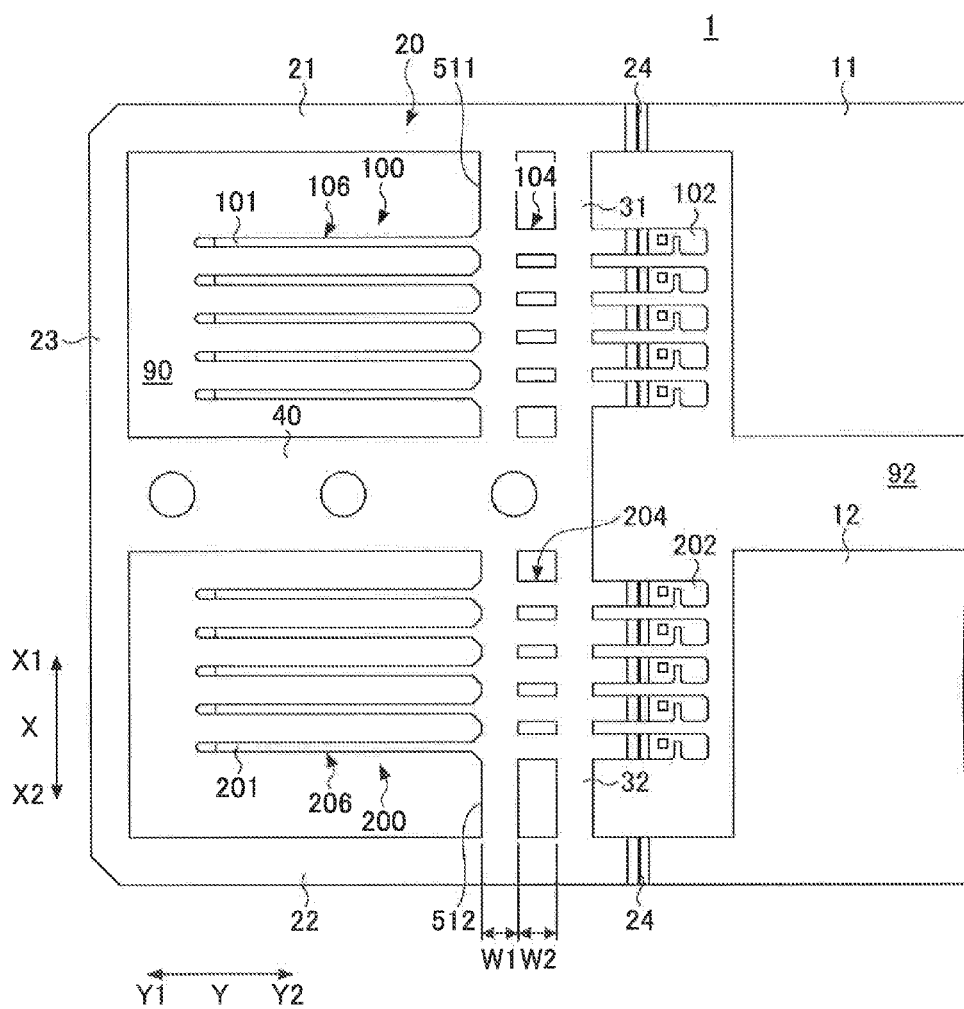


FIG. 3

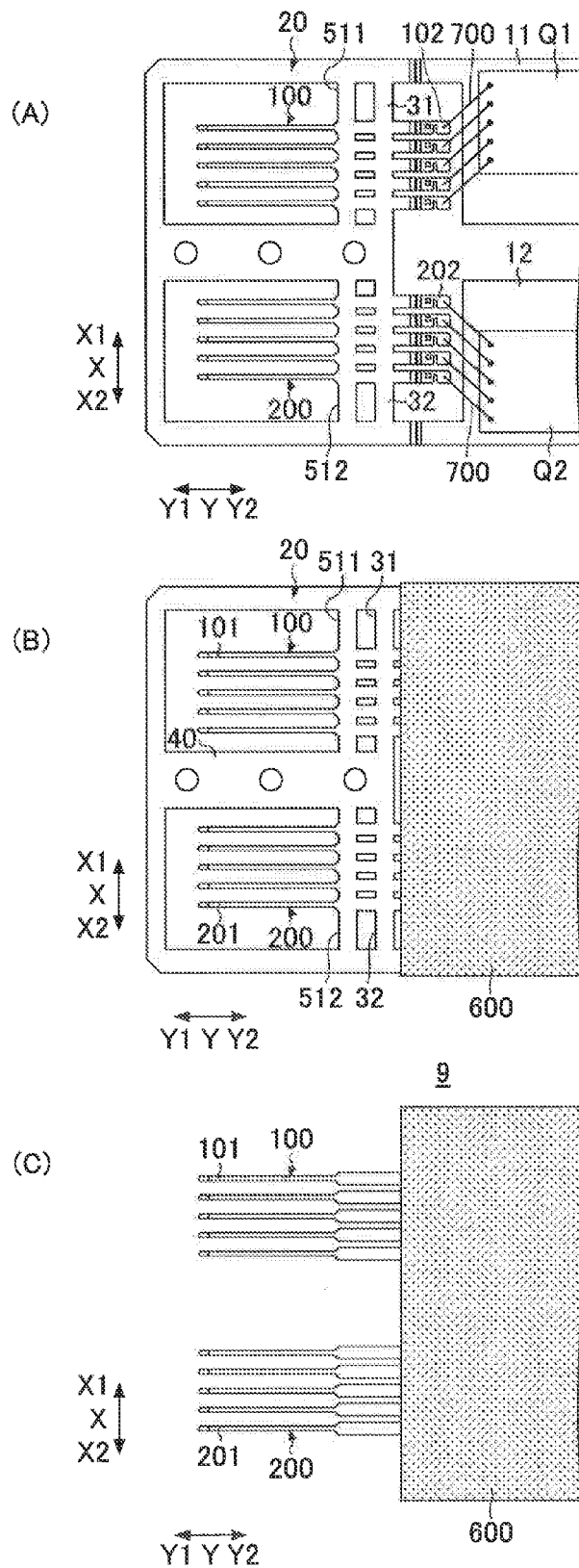


FIG. 4

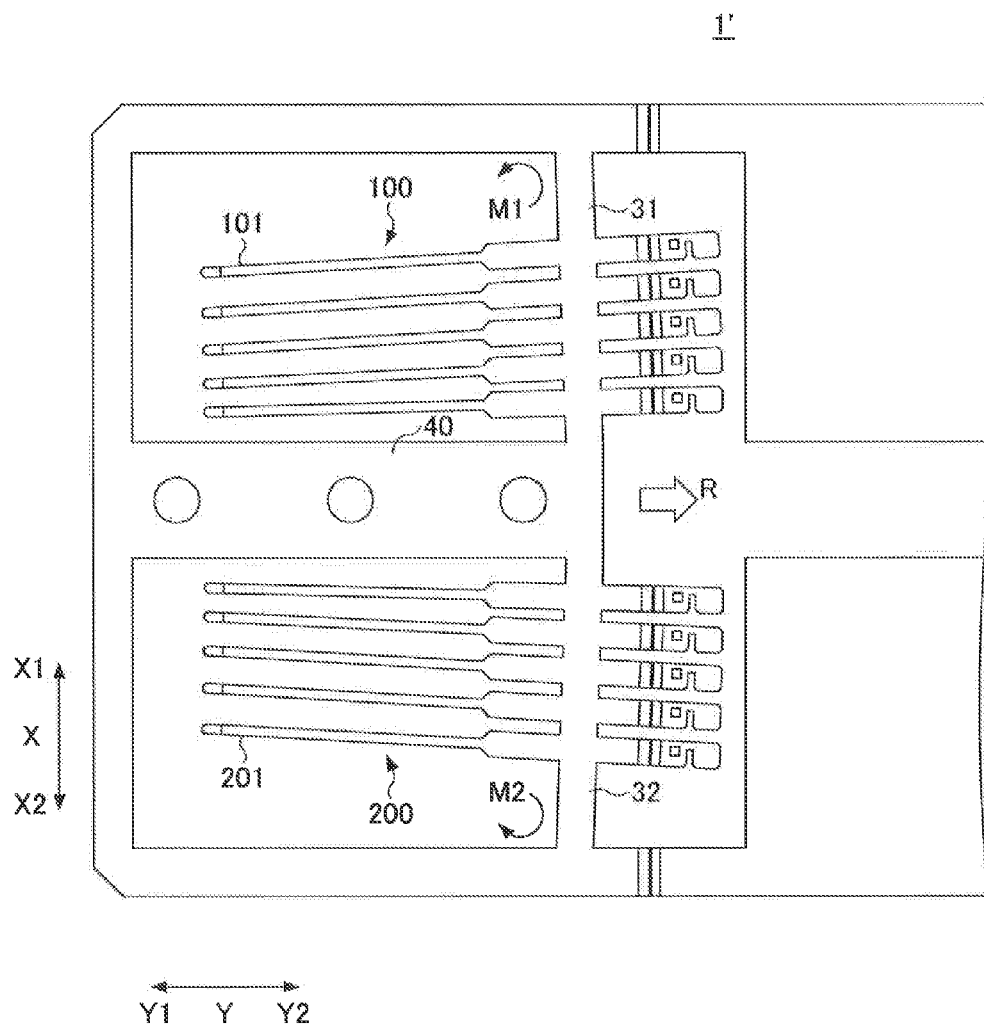


FIG.5

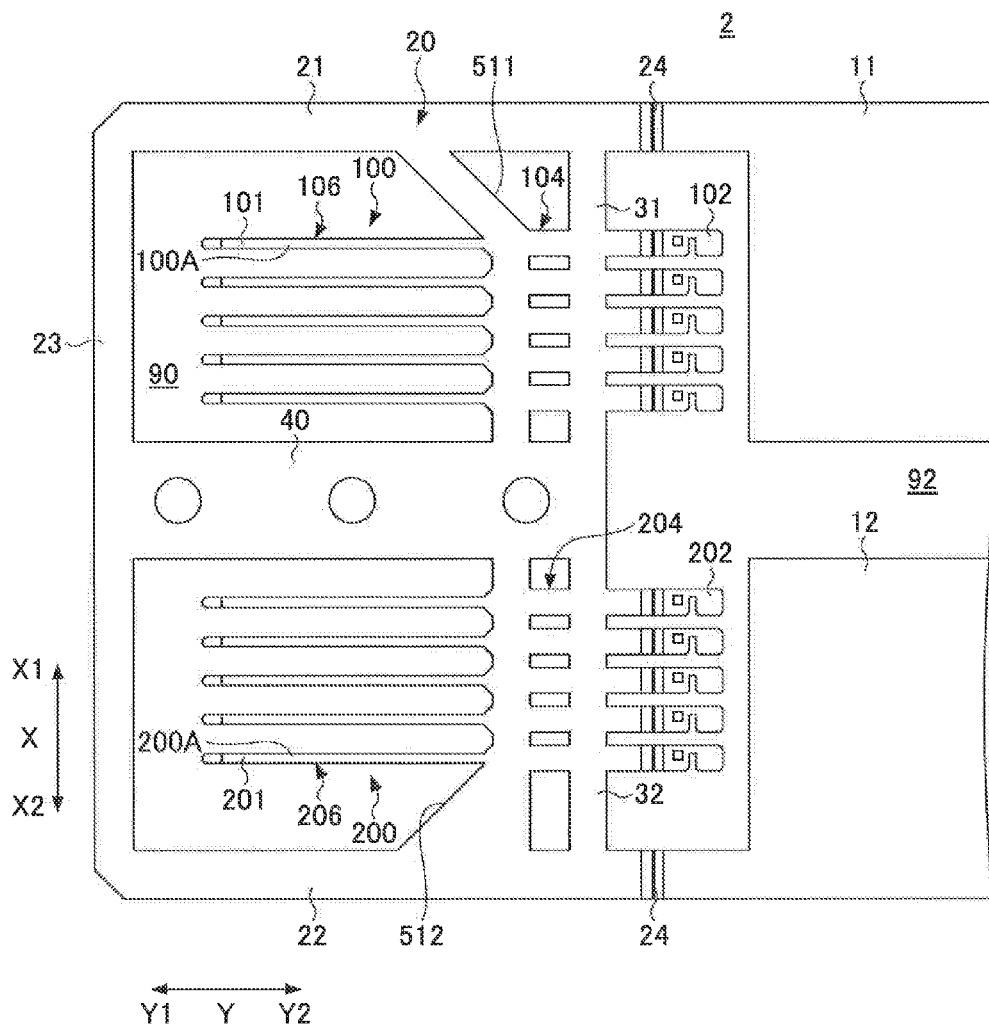


FIG. 6

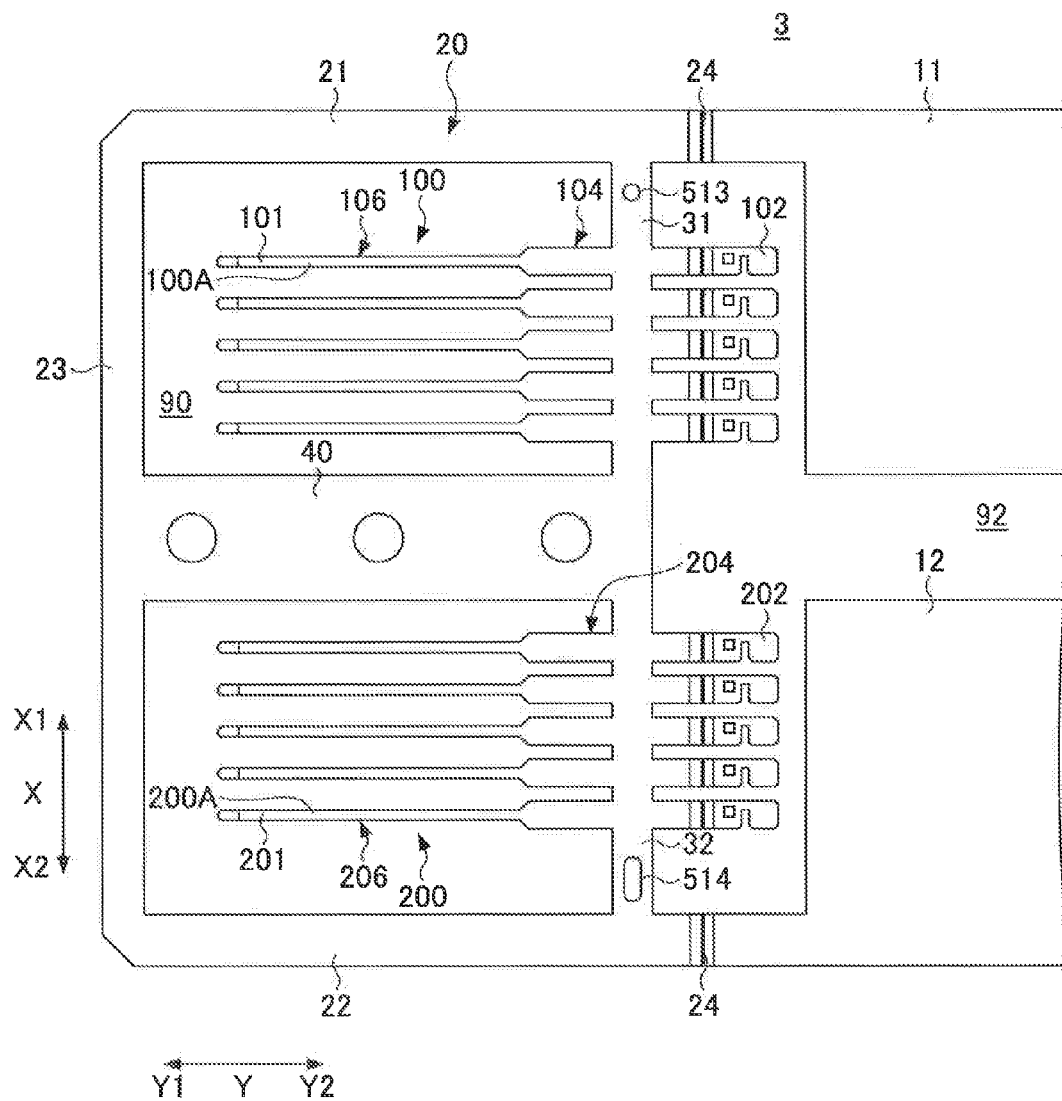


FIG. 7

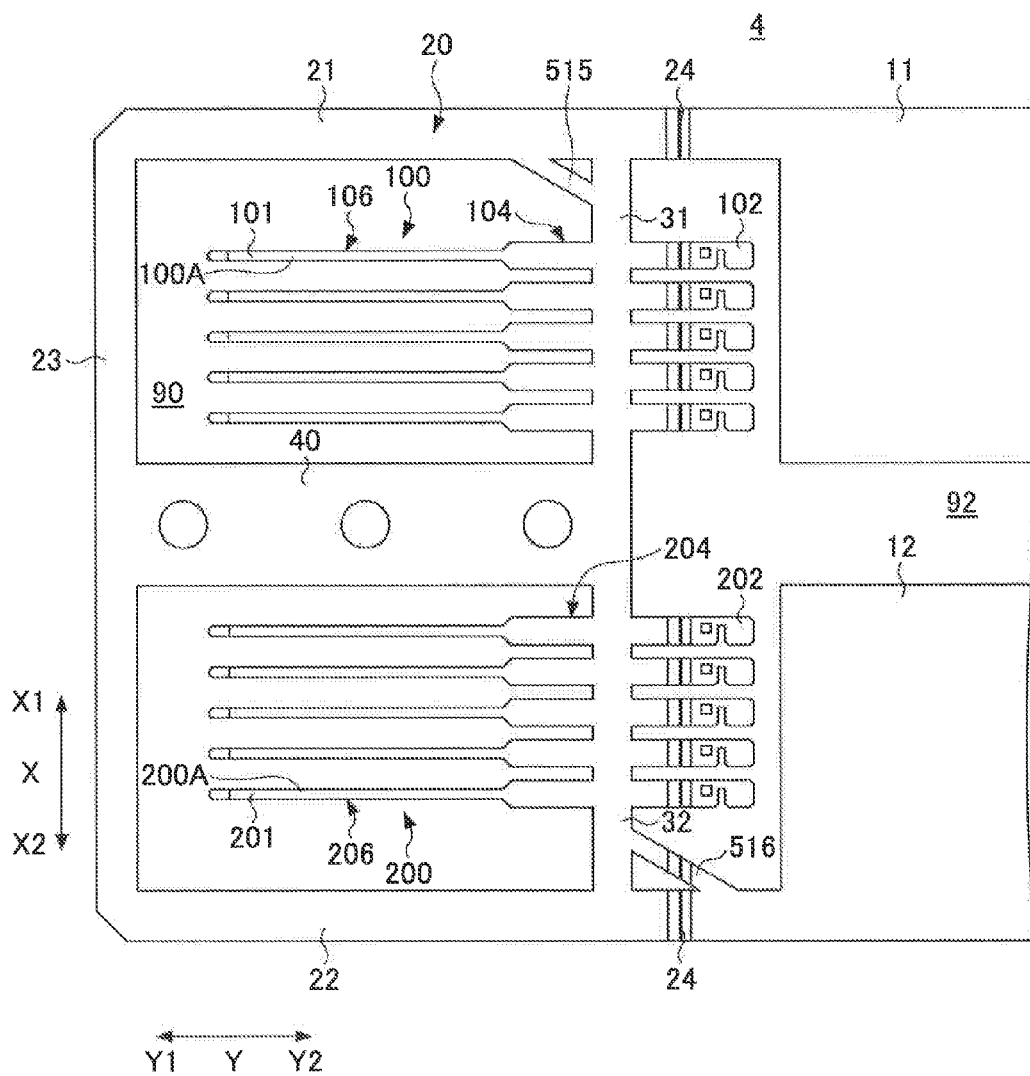
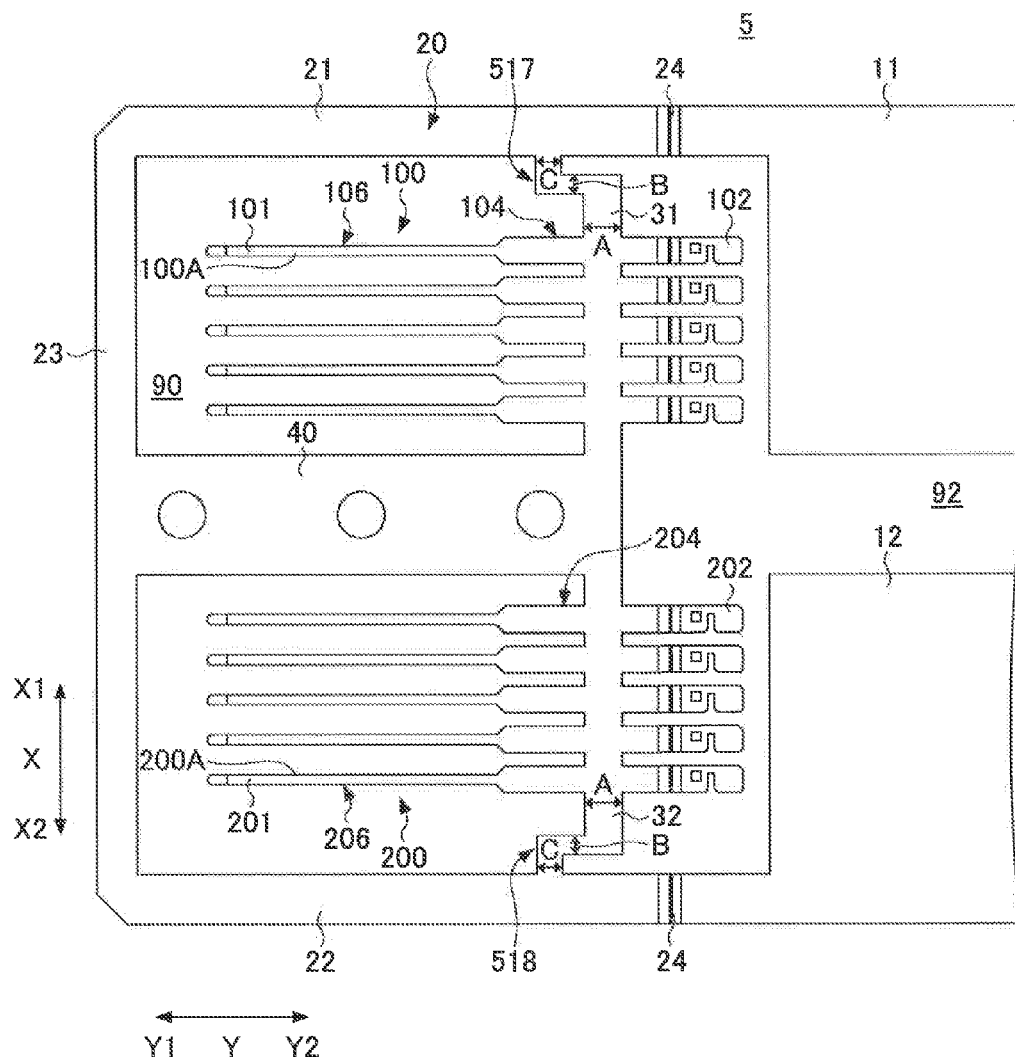


FIG. 8



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LEAD FRAME, ELECTRIC POWER CONVERTING DEVICE, SEMICONDUCTOR APPARATUS AND METHOD OF MANUFACTURING SEMICONDUCTOR APPARATUS

FIELD

This disclosure is related to a lead frame, an electric power converting device, a semiconductor apparatus and method of manufacturing a semiconductor apparatus.

BACKGROUND

A known lead frame is configured such that a lead frame body includes an island on which semiconductor chips are mounted; leads connected to the semiconductor chips via bonding wires; and tie bars for connecting the island and the leads to the lead frame body (see Patent Document 1: Japanese Laid-open Patent Publication No. 2008-218455, for example). The lead frame has a reinforcing protrusion part formed at a periphery of the lead frame body so that the lead frame body does not actually deform even when such a force that otherwise would deform the lead frame body is applied at the time of handling the lead frame, etc. Further, FIG. 21 in Patent Document 1 disclose a lead frame which includes a lead frame body in which islands and lead groups are provided in groups of three.

According to the configuration disclosed in Patent Document 1 (FIG. 21, in particular), intermediate portions that connect the respective lead groups are formed such that they pass between the islands to connect two opposite sides of the periphery of the lead frame body. Thus, according to the configuration disclosed in Patent Document 1, because of the existence of such intermediate portions, there is a problem that the distances between the islands need to be set such that necessary isolation distances are ensured between the islands and the intermediate portions, which prevents a downsizing of the lead frame and thus a semiconductor apparatus.

SUMMARY

According to one aspect of this disclosure, a lead frame is provided, which includes:

- a first island and a second island that are arranged side by side via a predetermined space in a first direction;
- an outer peripheral frame;
- a plurality of first leads that extend in a second direction perpendicular to the first direction such that the first leads are arranged side by side in the first direction, wherein each of the first leads has an external connection end at one end in the second direction and a semiconductor element connection end for connecting to a semiconductor element at the other end in the second direction;
- a plurality of second leads that extend in the second direction such that the second leads are arranged side by side in the first direction, wherein each of the second leads has an external connection end at one end in the second direction and a semiconductor element connection end for connecting to a semiconductor element at the other end in the second direction;
- a first coupling portion that couples the first leads to the outer peripheral frame such that the first coupling portion crosses the first leads;

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- a second coupling portion that couples the second leads to the outer peripheral frame such that the second coupling portion crosses the second leads;
- an intermediate portion that is formed between the first and second coupling portions in the first direction such that the intermediate portion couples the first coupling portion to the second coupling portion, wherein the intermediate portion extends in the second direction to terminate before the predetermined space between the first and second islands; and
- a deformation restraining portion configured to restrain deformations of the first and second leads during a molding process, wherein the deformation restraining portion is formed or provided in at least one of the first leads, the second leads, the first coupling portion and the second coupling portion.

BRIEF DESCRIPTION OF DRAWINGS

FIG. 1 is a diagram for illustrating an overview of an example of a motor drive system **1000** for an electric vehicle.

FIG. 2 is a plane view for schematically illustrating a configuration of a lead frame **1** according to an embodiment (a first embodiment).

FIG. 3 is a diagram for explaining an example of a way of manufacturing an inverter **1003**.

FIG. 4 is a diagram for schematically illustrating a deformed status of a lead frame **1'** according to a comparative example during a resin molding process.

FIG. 5 is a plane view for schematically illustrating a configuration of a lead frame **2** according to another embodiment (a second embodiment).

FIG. 6 is a plane view for schematically illustrating a configuration of a lead frame **3** according to yet another embodiment (a third embodiment).

FIG. 7 is a plane view for schematically illustrating a configuration of a lead frame **4** according to yet another embodiment (a fourth embodiment).

FIG. 8 is a plane view for schematically illustrating a configuration of a lead frame **5** according to yet another embodiment (a fifth embodiment).

DESCRIPTION OF EMBODIMENTS

In the following, embodiments are described in detail with reference to appended drawings.

Here, at first, a motor drive system for an electric vehicle is described. FIG. 1 is a diagram for illustrating an overview of an example of a motor drive system **1000** for an electric vehicle. The motor drive system **1000** is a system for driving a motor **1004** for driving a vehicle using power from a battery **1001**. It is noted that a type of the electric vehicle or a detailed configuration of the electric vehicle may be arbitrary as long as the electric vehicle is driven with a motor **1004** using electric power. Typically, the electric vehicle includes a hybrid vehicle (HV) which uses an internal combustion engine and the motor **1004** as a power source and a genuine electric vehicle which uses the motor **1004** only as a power source.

The motor drive system **1000** includes the battery **1001**, a DC-DC converter **1002**, an inverter **1003**, the motor **1004** and a control apparatus **1005**, as shown in FIG. 1.

The battery **1001** is an arbitrary capacitor cell which accumulates power to output a direct-voltage. The battery **1001** may be configured by a nickel hydrogen battery, a lithium ion battery or a capacitive element such as an electrical double layer capacitor, etc.

The DC-DC converter **1002** may be a bidirectional DC-DC converter (a reversible chopper type DC-DC converter).

The inverter **1003** includes arms of U-W-W phases disposed in parallel between a positive side line and the negative side line. The U-phase arm includes switching elements (IGBT: Insulated Gate Bipolar Transistor, in this example) Q1 and Q2 connected in series, the V-phase arm includes switching elements (IGBT in this example) Q3 and Q4 connected in series and W-phase arm includes switching elements (IGBT in this example) Q5 and Q6 connected in series. Further, diodes (free wheel diodes, for example) D1-D6 are provided between a collector and an emitter of each switching element Q1-Q6, respectively. It is noted that the switching elements Q1-Q6 may be transistors other than IGBTs, such as MOSFETs (metal oxide semiconductor field-effect transistor), etc.

The motor **1004** is a three-phase permanent-magnetic motor and one end of each coil of the U, V and W phases is commonly connected at a midpoint therebetween. It is noted that a way of connecting three coils of U, V and W phases may be a delta connection. It is noted that, in addition to the motor **1004**, a second motor for driving a vehicle or a generator may be added in parallel with respect to the motor **1004**. In this case, a corresponding inverter may be added in parallel.

The control apparatus **1005** controls the DC-DC converter **1002** and the inverter **1003**. A way of controlling the DC-DC converter **1002** and the inverter **1003** may be arbitrary.

FIG. 2 is a plane view for schematically illustrating a configuration of a lead frame **1** according to an embodiment (a first embodiment). An X-direction and a Y-direction which are perpendicular to each other as disclosed in FIG. 2 are used for the explanation hereinafter. Further, as an example, hereinafter it is assumed that the lead frame **1** forms upper and lower arms of the U phase of the inverter **1003**. However, the lead frame **1** may be used to form upper and lower arms of other phases of the inverter **1003** or upper and lower arms of the DC-DC converter **1002** described above as well as other semiconductor apparatuses. It is noted that, in the case of forming the inverter **1003** described above, three inverters **1003** described above may be used to form the upper and lower arms of three phases.

The lead frame **1** includes a first island **11**, a second island **12**, an outer peripheral frame **20**, first leads **100**, second leads **200**, a first coupling portion **31**, a second coupling portion **32**, an intermediate portion **40**, a first deformation restraining portion **511**, and a second deformation restraining portion **512**. It is noted that the lead frame **1** may include portions with different thicknesses. In this case, a thick portion with a relatively great thickness may form the first and second islands **11** and **12**, and a thin portion with a relatively small thickness may form other portions. Alternatively, a part of the outer peripheral frame **20** may be formed by the thick portion. In a typical case, a ratio of the thickness between the thick portion and the thin portion is 4:1. However, the thick portion may have a thickness which is greater than four times of the thickness of the thin portion in order to increase a heat sink function.

The first and second islands **11** and **12** may be disposed side by side via a predetermined space (clearance) **92**. Semiconductor elements are mounted on the first and second islands **11** and **12**, respectively. In this example, the IGBT and the diode (free wheel diode) that form the upper arm of the U phase of the inverter **1003** are mounted on the first island **11**, and the IGBT and the diode that form the lower arm of the U phase of the inverter **1003** are mounted on the second island **12**. It is noted that, in the example illustrated in FIG. 2, the first and second islands **11** and **12** are arranged side by side in the

X-direction without any offset in the Y-direction; however, the first and second islands **11** and **12** may be arranged side by side in the X-direction with an offset in the Y-direction.

The outer peripheral frame **20** forms an outer peripheral frame of the lead frame **1**, and may have functions of ensuring necessary rigidity of the lead frame **1** as well as holding (suspending) the first leads **100**, etc. A detailed shape of the outer peripheral frame **20** may be arbitrary. It is noted that, in the example illustrated in FIG. 2, the outer peripheral frame **20** is formed on a Y1 side in the Y-direction with respect to the first and second islands **11** and **12**. Specifically, the outer peripheral frame **20** includes a first lateral portion **21**, a second lateral portion **22** and a longitudinal portion **23**. The first lateral portion **21** extends from an end of the first island **11** on an X1 side in the X-direction to the Y1 side. The second lateral portion **22** extends from an end of the second island **12** on an X2 side in the X-direction to the Y1 side. The longitudinal portion **23** extends in the X-direction to couple an end of the first lateral portion **21** and an end of the second lateral portion **22**. The first and second lateral portions **21** and **22** and the longitudinal portion **23** define, in cooperation with the first and second islands **11** and **12**, a substantially closed opening **90**. However, a space **92** is formed between the first and second islands **11** and **12**. The outer peripheral frame **20** may be formed on a Y2 side in the Y-direction with respect to the first and second islands **11** and **12**. In this case, the first and second islands **11** and **12** may be coupled to the outer peripheral frame **20** on the Y2 side as well. Further, in the example illustrated in FIG. 2, the first and second lateral portions **21** and **22** have steps **24** via which the first and second lateral portions **21** and **22** are connected to the first and second islands **11** and **12**, respectively.

The first leads **100** are disposed side by side in the X-direction. The first leads **100** each extend in the Y-direction. The first leads **100** each include an external connection end **101** on the Y1 side in the Y-direction, and a semiconductor element connection end **102** on the Y2 side in the Y-direction. It is noted that, in the example illustrated in FIG. 2, the first leads **100** each include a wide portion **104** on the Y2 side in the Y-direction that has a relatively great width in the X-direction, and a narrow portion **106** on the Y1 side in the Y-direction that has a relatively small width in the X-direction. However, the first leads **100** each may have a constant width or a width that varies in a different way. It is noted that the external connection ends **101** may be formed on ends of the narrow portions **106**. The first leads **100** may be plated by nickel plating, etc., for example. Further, the external connection ends **101** may be specially plated by gold plating, etc., for example.

It is noted that, in the example illustrated in FIG. 2, the first leads **100** are disposed next to the first island **11** on the Y1 side in the Y-direction with respect to the first island **11**. However, the first leads **100** may be disposed such that the first leads **100** have an offset in the X-direction with respect to the first island **11**. Further, in the example illustrated in FIG. 2, the first leads **100** each are arranged side by side in the X-direction without any offset in the Y-direction; however, the first leads **100** each may be arranged side by side in the X-direction with an offset in the Y-direction.

The second leads **200** are disposed side by side in the X-direction. The second leads **200** each extend in the Y-direction. The second leads **200** each includes an external connection end **201** on the Y1 side in the Y-direction, and a semiconductor element connection end **202** on the Y2 side in the Y-direction. It is noted that, in the example illustrated in FIG. 2, the second leads **200** each include a wide portion **204** on the Y2 side in the Y-direction that has a relatively great width in the X-direction, and a narrow portion **206** on the Y1

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side in the Y-direction that has a relatively small width in the X-direction. However, the second leads **200** each may have a constant width or a width that varies in a different way. It is noted that the external connection ends **201** may be formed on ends of the narrow portions **206**. The second leads **200** may be plated by nickel plating, etc., for example. Further, the external connection ends **201** may be specially plated by gold plating, etc., for example.

It is noted that, in the example illustrated in FIG. 2, the second leads **200** are disposed next to the second island **12** on the Y1 side in the Y-direction with respect to the second island **12**. However, the second leads **200** may be disposed such that the second leads **200** have an offset in the X-direction with respect to the second island **12**. Further, the second leads **200** and the first leads **100** are disposed side by side in the X-direction. However, the second leads **200** and the first leads **100** may be disposed side by side in the X-direction such that the second leads **200** have an offset in the Y-direction with respect to the first leads **100**. Further, in the example illustrated in FIG. 2, the second leads **200** each are arranged side by side in the X-direction without any offset in the Y-direction; however, the second leads **200** each may be arranged side by side in the X-direction with an offset in the Y-direction.

The first coupling portion **31** crosses the first leads **100** to couple the first leads **100** to the outer peripheral frame **20**. In other words, the first coupling portion **31** functions as a tie bar for suspending the first leads **100** with respect to the outer peripheral frame **20**. In the example illustrated in FIG. 2, the first coupling portion **31** extends from the first lateral portion **21** in a direction parallel to the X-direction such that the first coupling portion **31** couples between the wide portions **104** of the first leads **100** and couples to the intermediate portion **40** described hereinafter. It is noted that the first coupling portion **31** may be formed on the Y1 side in the Y-direction with respect to the step **24** of the first lateral portion **21**.

The second coupling portion **32** crosses the second leads **200** to couple the second leads **200** to the outer peripheral frame **20**. In other words, the second coupling portion **32** functions as a tie bar for suspending the second leads **200** with respect to the outer peripheral frame **20**. In the example illustrated in FIG. 2, the second coupling portion **32** extends from the second lateral portion **22** in a direction parallel to the X-direction such that the second coupling portion **32** couples between the wide portions **204** of the second leads **200** and couples to the intermediate portion **40** described hereinafter. It is noted that the first coupling portion **32** may be formed on the Y1 side in the Y-direction with respect to the step **24** of the first lateral portion **22**.

It is noted that, in the example illustrated in FIG. 2, the first and second coupling portions **31** and **32** don't have an offset in the Y-direction with respect to each other such that the first and second coupling portions **31** and **32** extend in a straight line as a whole; however, the first and second coupling portions **31** and **32** may have an offset in the Y-direction.

The intermediate portion **40** is formed between the first and second coupling portions **31** and **32** to couple to the first and second coupling portions **31** and **32**. An extension (existing range on the Y2 side in the Y-direction) of the intermediate portion **40** in the Y-direction ends before the space **92** between the first and second islands **11** and **12**. In other words, the intermediate portion **40** is formed in the Y-direction such that the intermediate portion **40** does not extend into (enter) the space **92** between the first and second islands **11** and **12**. With this arrangement, the distance (in the X-direction) between the first and second islands **11** and **12** can be reduced and the lead frame **1** (and thus the inverter **1003** that is formed by the lead frame **1**) can be downsized. In other words, if the inter-

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mediate portion **40** extends into the space **92** between the first and second islands **11** and **12**, it becomes necessary to increase the distance between the first and second islands **11** and **12** so as to ensure insulation between the first and second islands **11** and **12** and the intermediate portion **40** (and between the semiconductor element connection ends **102**, **202** and the intermediate portion **40**). In contrast, in the example illustrated in FIG. 2, because the intermediate portion **40** does not extend between the first and second islands **11** and **12**, it becomes possible to minimize the distance between the first and second islands **11** and **12** and thus downsize the lead frame **1**. In the example illustrated in FIG. 2, the intermediate portion **40** is not formed on the Y2 side in the Y-direction with respect to the first and second coupling portions **31** and **32** such that the intermediate portion **40** on the Y2 side in the Y-direction terminates between first and second coupling portions **31** and **32**. Thus, it is substantially unnecessary to take care of the insulation between the semiconductor element connection ends **102**, **202** and the intermediate portion **40**.

It is noted that such a configuration as described above in which the intermediate portion **40** on the Y2 side in the Y-direction does not pass between the first and second islands **11** and **12** (and thus the intermediate portion **40** on the Y2 side in the Y-direction is not suspended by the outer peripheral frame **20**) is referred to as "cantilever configuration", hereinafter.

The intermediate portion **40** on the Y1 side in the Y-direction need not extend to the outer peripheral frame **20**; however, preferably the intermediate portion **40** on the Y1 side in the Y-direction couples to the outer peripheral frame **20**, as illustrated in FIG. 2. With this arrangement, the rigidity of the outer peripheral frame **20** increases and the deformation of the outer peripheral frame **20** (and thus the deformation of the first and second leads **100** and **200**) can be reduced. It is noted that, in the example illustrated in FIG. 2, the intermediate portion **40** has a width in the X-direction that is substantially equal to the distance in the X-direction between the first and second islands **11** and **12**, and extends in a direction parallel to the Y-direction.

The first deformation restraining portion **511** has a function of restraining deformations of the first leads **100** during a molding process (this deformation restraining function is described in detail, hereinafter). The first deformation restraining portion **511** crosses the first leads **100** to couple the first leads **100** to the outer peripheral frame **20**. In other words, the first deformation restraining portion **511** functions as a tie bar for suspending the first leads **100** with respect to the outer peripheral frame **20**, as is the case with the first coupling portion **31**. In the example illustrated in FIG. 2, the first deformation restraining portion **511** extends from the first lateral portion **21** in a direction parallel to the X-direction such that the first deformation restraining portion **511** couples between the wide portions **104** of the first leads **100** and couples to the intermediate portion **40**. It is noted that the first deformation restraining portion **511** may be formed on the Y1 side in the Y-direction with respect to the first coupling portion **31**.

The second deformation restraining portion **512** has a function of restraining deformations of the second leads **200** during the molding process (this deformation restraining function is described in detail, hereinafter). The second deformation restraining portion **512** crosses the second leads **200** to couple the second leads **200** to the outer peripheral frame **20**. In other words, the second deformation restraining portion **512** functions as a tie bar for suspending the second leads **200** with respect to the outer peripheral frame **20**, as is

the case with the second coupling portion **32**. In the example illustrated in FIG. **2**, the second deformation restraining portion **512** extends from the second lateral portion **22** in a direction parallel to the X-direction such that the second deformation restraining portion **512** couples between the wide portions **204** of the second leads **200** and couples to the intermediate portion **40**. It is noted that the second deformation restraining portion **512** may be formed on the Y1 side in the Y-direction with respect to the second coupling portion **32**.

It is noted that, in the example illustrated in FIG. **2**, the first and second deformation restraining portions **511** and **512** don't have an offset in the Y-direction with respect to each other such that the first and second deformation restraining portions **511** and **512** extend in a straight line as a whole; however, the first and second deformation restraining portions **511** and **512** may have an offset in the Y-direction.

Next, a way of manufacturing the inverter **1003** using the lead frame **1** is described. FIG. **3** is a diagram for explaining an example of a way of manufacturing the inverter **1003**.

At first, the lead frame illustrated in FIG. **2** is provided, and then the IGBT and the diode (free wheel diode) are installed on the first and second islands **11** and **12** of the lead frame **1**, respectively. It is noted that the IGBT and the diode may be mounted on the first and second islands **11** and **12** of the lead frame **1**, respectively, by soldering or the like. In FIG. **3** (A), for the sake of convenience for the explanation, only the switching elements Q1 and Q2 which are IGBTs mounted on the first and second islands **11** and **12** of the lead frame **1**, respectively, are illustrated. The diodes may be installed on the Y2 side in the Y-direction with respect to the IGBTs.

Then, as illustrated in FIG. **3** (A), the semiconductor element connection ends **102** of the first leads **100** are connected to the switching element Q1, by bonding wires **700**, for example, and the semiconductor element connection ends **202** of the second leads **200** are connected to the switching element Q2, by bonding wires **700**, for example. It is noted that the first leads and the second leads **200** becomes leads for transmitting gate signals (driving signals for the switching elements Q1 and Q2), signals related to sense emitters (for detecting excessive current) that may be incorporated in the switching elements Q1 and Q2, signals related to temperature sensors, etc. Other processes, which are not illustrated, such as other connections of the switching elements Q1 and Q2 (connections between emitters of the switching elements Q1 and Q2 and anodes of the diodes D1 and D2, respectively, for example) may be performed. Further, prior to a subsequent resin molding process, the lead frame **1** may be provided on a heat sink or the like via an insulation body.

Then, as illustrated in FIG. **3** (B), a resin is molded on the lead frame **1** such that the external connection ends **101** of the first leads and the external connection end **201** of the second leads are exposed to the outside (a resin molding process). In other words, the semiconductor element connection ends **102** and **203**, the switching elements Q1 and Q2, etc., are sealed by the resin. As a result of this, as illustrated in FIG. **3** (B), a resin mold portion **600** is formed on the lead frame **1**.

Then, as illustrated in FIG. **3** (C), a part of the outer peripheral frame **20** that is exposed from the resin mold portion **600**, the first coupling portion **31**, the second coupling portion **32**, the intermediate portion **40**, the first deformation restraining portion **511**, and the second deformation restraining portion **512** are cut away. As a result of this, a configuration in which only the first and second leads **100** and **200** are exposed from the resin mold portion **600** is obtained. Further, the first and second leads **100** and **200** may be subject to a forming process to have their final shapes. In this way, an electric power

converting device **9** is formed. Then, although it is not illustrated, the external connection ends **101** of the first leads **100** and the external connection ends **201** of the second leads **200** may be connected to a control substrate that implements the control apparatus **1005**.

It is noted that, in the example illustrated in FIG. **3**, only the first and second leads **100** and **200** are exposed from the resin mold portion **600**; however, other portions may be exposed if necessary. For example, if a part of the portion of the outer peripheral frame **20** exposed from the resin mold portion **600** is utilized to form a lead portion for a voltage sensor, the part may be remained (exposed) without being cut away.

When such a resin molding process as illustrated in FIG. **3** (C) is performed, the lead frame **1** is pressed down by a die. Typically, the first coupling portion **31**, the second coupling portion **32**, the opposite ends of the intermediate portion **40** in the Y-direction, etc., are pressed down by the die so that the resin molding process is performed in a status where the lead frame **1** is stationary (fixed). At that time, a force is applied the lead frame **1** when the lead frame **1** is pressed down by the die. Therefore, it is desirable that the lead frame **1** is formed such that no harmful deformation occurs at the time of the resin molding process.

FIG. **4** is a diagram for schematically illustrating a deformed status of a lead frame **1'** according to a comparative example during a resin molding process. The comparative example differs from the first embodiment described above in that it does not include the first deformation restraining portion **511** and the second deformation restraining portion **512**.

When the lead frame **1'** is pressed down by the die at the time of the resin molding process, rotation moments M1 and M2 are applied to the lead frame **1'**. This is because the outer peripheral frame **20** is pressed down strongly by the die at a portion which is adjacent to the end of the first coupling portion **31** on the X1 side and portion which is adjacent to the end of the second coupling portion **32** on the X2 side, in particular, while the intermediate portion **40** is not constrained on the Y2 side due to the cantilever configuration described above. Thus, as indicated by an arrow R in FIG. **4**, the intermediate portion **40** is deformed (displaced) toward the Y2 side, and the first leads **100** and the second leads **200** are deformed such that the first leads **100** and the second leads **200** come closer to each other on the side of the external connection ends **101**, as illustrated in FIG. **4**.

In contrast, according to the first embodiment described above, such deformations can be reduced because the first deformation restraining portion **511** and the second deformation restraining portion **512** are provided. Specifically, according to the first embodiment, because the first deformation restraining portion **511** and the second deformation restraining portion **512** are provided, overall bending rigidity of the first deformation restraining portion **511**, the second deformation restraining portion **512**, the first coupling portion **31** and the second coupling portion **32** are increased, which reduces the displacement of the intermediate portion **40** to the Y2 side. Further, thanks to a clearance between the first deformation restraining portion **511** and the first coupling portion **31** and a clearance between the second deformation restraining portion **512** and the second coupling portion **32**, the deformations of the first and second leads **100** and **200** are absorbed on the Y2 side with respect to the first deformation restraining portion **511** and the second deformation restraining portion **512**, which reduces the deformations of the first and second leads **100** and **200** on the side of the external connection ends **101** and **201**. It is noted that a CAE (Computer-Aided Engineering) analysis performed by the inventors proved that the deformation amounts are reduced by

about 80 percent with respect to the comparative example. In particular, when a sum ($=W1+W2$) of a width $W1$ (see FIG. 2) in the Y-direction of the first deformation restraining portion **511** and the second deformation restraining portion **512** and a width $W2$ in Y-direction of a clearance between the first and the second deformation restraining portions **511** and **512** and the first and second coupling portions **31** and **32** is greater than 4 mm, the deformation amounts can be reduced with increased robustness.

It is noted that in the first embodiment described above, the first and the second deformation restraining portions **511** and **512** are formed such that the first and the second deformation restraining portions **511** and **512** crosses the wide portions **104** and **204** of the first and second leads **100** and **200**, respectively. However, the first and the second deformation restraining portions **511** and **512** may be formed such that they cross any portions of the first and second leads **100** and **200**, respectively, as long as the first and the second deformation restraining portions **511** and **512** are formed on the Y1 side with respect to the first and second coupling portions **31** and **32**, respectively. In this connection, ultimately, the first and the second deformation restraining portions **511** and **512** may be formed integrally with the first and second coupling portions **31** and **32** (i.e., the clearance $W2=0$), respectively. Further, the first and the second deformation restraining portions **511** and **512** may be formed across the external connection ends **101** and **201** (tip portions on the Y1 side, for example) of the first and second leads **100** and **200**, respectively. However, if the first and the second deformation restraining portions **511** and **512** are formed across the external connection ends **101** and **201** of the first and second leads **100** and **200**, respectively, the plating (gold plating, for example) may come off such that a surface under the plating is exposed at the time of cutting the first and the second deformation restraining portions **511** and **512** after the resin molding process. In this case, a reliability of the electric connection at the external connection ends **101** and **201** may be reduced. Thus, preferably, the first and the second deformation restraining portions **511** and **512** are formed across portions other than the external connection ends **101** and **201** of the first and second leads **100** and **200**, respectively.

FIG. 5 is a plane view for schematically illustrating a configuration of a lead frame **2** according to another embodiment (a second embodiment). The second embodiment differs from the first embodiment described above in the configurations of the first and the second deformation restraining portions **511** and **512**. Other configurations in the second embodiment may be the same as those in the first embodiment described above.

Specifically, according to the second embodiment, the first deformation restraining portion **511** extends in an inclined direction between the outer peripheral frame **20** and the outermost first lead **100A** of the first leads **100** on the X1 side. In other words, the first deformation restraining portion **511** extends straightly in a direction parallel to the X-direction between the intermediate portion **40** and the outermost first lead **100A** of the first leads **100** on the X1 side, while the first deformation restraining portion **511** is inclined between the outer peripheral frame **20** and the outermost first lead **100A** such that the first deformation restraining portion **511** on the side of the outer peripheral frame **20** is directed to the Y1 side. Also in this case, substantially the same effects as the first embodiment described above can be obtained.

Further, according to the second embodiment, the second deformation restraining portion **512** has such a width in the Y-direction between the outer peripheral frame **20** and the outermost second lead **200A** of the second leads **200** on the

X2 side that the width gradually becomes greater as the second deformation restraining portion **512** comes closer to the outer peripheral frame **20**. In other words, the second deformation restraining portion **512** extends straight in a direction parallel to the X-direction between the intermediate portion **40** and the outermost second lead **200A** of the second leads **200** on the X2 side, while the second deformation restraining portion **512** has such a width in the Y-direction between the outer peripheral frame **20** and the outermost second lead **200A** that the width gradually becomes greater as the second deformation restraining portion **512** comes closer to the outer peripheral frame **20**. Also in this case, substantially the same effects as the first embodiment described above can be obtained.

It is noted that, in the second embodiment, the respective configurations of the first and the second deformation restraining portions **511** and **512** are different; however, they may be the same. In other words, in the second embodiment, the first deformation restraining portion **511** may have the same configuration as the second deformation restraining portion **512** according to the second embodiment. Alternatively, in the second embodiment, the second deformation restraining portion **512** may have the same configuration as the first deformation restraining portion **511** according to the second embodiment. Further, the second deformation restraining portion **512** has the width in the Y-direction that increases linearly as a position on the second deformation restraining portion **512** changes from the outermost second lead **200A** to the outer peripheral frame **20**; however, the width in the Y-direction may increase non-linearly.

FIG. 6 is a plane view for schematically illustrating a configuration of a lead frame **3** according to yet another embodiment (a third embodiment). The third embodiment differs from the first embodiment described above in the configurations of the first and the second deformation restraining portions. Other configurations in the third embodiment may be the same as those in the first embodiment described above.

Specifically, according to the third embodiment, the first and the second deformation restraining portions **511** and **512** in a form of a tie bar are omitted, and, instead of it, first and second deformation restraining portions **513** and **514** in a form of a hole are provided.

The first deformation restraining portion **513** is formed in the first coupling portion **31** between the outer peripheral frame **20** and the outermost first lead **100A** of the first leads **100** on the X1 side, as illustrated in FIG. 6. In other words, the first deformation restraining portion **513** is not formed in the first coupling portion **31** between the intermediate portion **40** and the outermost first lead **100A** so that the first deformation restraining portion **513** is formed only in an end portion of the first coupling portion **31** on the X1 side.

The second deformation restraining portion **514** is formed in the second coupling portion **32** between the outer peripheral frame **20** and the outermost second lead **200A** of the second leads **200** on the X2 side, as illustrated in FIG. 6. In other words, the second deformation restraining portion **514** is not formed in the second coupling portion **32** between the intermediate portion **40** and the outermost second lead **200A** so that the second deformation restraining portion **514** is formed only in an end portion of the second coupling portion **32** on the X2 side.

According to the third embodiment, thanks to the first and second deformation restraining portions **513** and **514** in a form of a hole, the first and second deformation restraining portions **513** and **514** are locally deformed at the time of the resin molding process, which reduces the deformation of the

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lead frame **3** as a whole (i.e., the rotation moments M1 and M2 (see FIG. 4) are reduced). Therefore, as is the case with the first embodiment, it becomes possible to reduce the deformation of the first and second leads **100** and **200** on the side of the external connection ends **101** and **201**. It is noted that a CAE analysis performed by the inventors proved that the deformation amounts are reduced by about 20 percent with respect to the comparative example.

It is noted that, in the example illustrated in FIG. 6, the first deformation restraining portion **513** is in a form of a circular hole and the second deformation restraining portion **514** is in a form of a slot that has a longitudinal direction in the X-direction; however, shapes of the holes may be arbitrary. Further, the first deformation restraining portion **513** and/or the second deformation restraining portion **514** may include a plurality of holes.

FIG. 7 is a plane view for schematically illustrating a configuration of a lead frame **4** according to yet another embodiment (a fourth embodiment). The fourth embodiment differs from the first embodiment described above in the configurations of the first and the second deformation restraining portions. Other configurations in the fourth embodiment may be the same as those in the first embodiment described above.

Specifically, according to the fourth embodiment, the first and the second deformation restraining portions **511** and **512** in a form of a tie bar is omitted, and instead of it first and second deformation restraining portions **515** and **516** in a form of a beam (truss) are provided.

The first deformation restraining portion **515** is formed between the outer peripheral frame **20** and the outermost first lead **100A** of the first leads **100** on the X1 side such that one end of the first deformation restraining portion **515** is coupled to the outer peripheral frame **20** and another end of the first deformation restraining portion **515** is coupled to the first coupling portion **31**, as illustrated in FIG. 7. The first deformation restraining portion **515** may be formed on the Y1 side in the Y-direction with respect to the first coupling portion **31**, illustrated in FIG. 7. The first deformation restraining portion **515** may be formed integrally with the lead frame **4**, or may be formed separately from the lead frame **4** and then attached to the lead frame **4**.

The second deformation restraining portion **516** is formed between the outer peripheral frame **20** and the outermost second lead **200A** of the second leads **200** on the X2 side such that one end of the second deformation restraining portion **516** is coupled to the outer peripheral frame **20** and another end of the second deformation restraining portion **516** is coupled to the second coupling portion **32**, as illustrated in FIG. 7. The second deformation restraining portion **516** may be formed on the Y2 side in the Y-direction with respect to the second coupling portion **32**, illustrated in FIG. 7. The second deformation restraining portion **516** may be formed integrally with the lead frame **4**, or may be formed separately from the lead frame **4** and then attached to the lead frame **4**.

According to the fourth embodiment, thanks to the first and second deformation restraining portions **515** and **516** in a form of a beam, the bending rigidity of the first and second coupling portions **31** and **32** is increased and thus the deformation of the lead frame **3** as a whole at the time of the molding process is reduced. Therefore, according to the fourth embodiment, as is the case with the first embodiment described above, the deformations of the first and second leads **100** and **200** on the side of the external connection ends **101** and **201** can be reduced.

It is noted that, in the fourth embodiment, the respective configurations of the first and the second deformation

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restraining portions **515** and **516** are different; however, they may be the same. In other words, in the fourth embodiment, the first deformation restraining portion **515** may have the same configuration as the second deformation restraining portion **516** according to the fourth embodiment. Alternatively, in the fourth embodiment, the second deformation restraining portion **516** may have the same configuration as the first deformation restraining portion **515** according to the fourth embodiment. Further, a plurality of the first deformation restraining portions **515** and/or a plurality of the second deformation restraining portions **516** may be provided.

FIG. 8 is a plane view for schematically illustrating a configuration of a lead frame **5** according to yet another embodiment (a fifth embodiment). The fifth embodiment differs from the first embodiment described above in the configurations of the first and the second deformation restraining portions. Other configurations in the fifth embodiment may be the same as those in the first embodiment described above.

Specifically, according to the fifth embodiment, the first and the second deformation restraining portions **511** and **512** in a form of a tie bar is omitted, and, instead of it, first and second deformation restraining portions **517** and **518** in a form of a bent portion are provided.

The first deformation restraining portion **517** is formed in the first coupling portion **31** such that it is bent from the X-direction to the Y-direction and then from the Y-direction to the X-direction, as illustrated in FIG. 8. Specifically, the first deformation restraining portion **517** is formed in the first coupling portion **31** between the outer peripheral frame **20** and the outermost first lead **100A** of the first leads **100** on the X1 side. In other words, the first deformation restraining portion **517** is not formed in the first coupling portion **31** between the intermediate portion **40** and the outermost first lead **100A** so that the first deformation restraining portion **517** is formed only in an end portion of the first coupling portion **31** on the X1 side. The width B of the first deformation restraining portion **517** in the Y-direction is smaller than the width A of the first coupling portion **31** in the Y-direction. Further, the width C of the first deformation restraining portion **517** in the X-direction may be smaller than or the same as the width A of the first coupling portion **31** in the Y-direction.

The second deformation restraining portion **518** is formed in the second coupling portion **32** such that it is bent from the X-direction to the Y-direction and then from the Y-direction to the X-direction, as illustrated in FIG. 8. Specifically, the second deformation restraining portion **518** is formed in the second coupling portion **32** between the outer peripheral frame **20** and the outermost second lead **200A** of the second leads **200** on the X2 side. In other words, the second deformation restraining portion **518** is not formed in the second coupling portion **32** between the intermediate portion **40** and the outermost second lead **200A** so that the second deformation restraining portion **518** is formed only in an end portion of the second coupling portion **32** on the X2 side. The width B of the second deformation restraining portion **518** in the Y-direction is smaller than the width A of the second coupling portion **32** in the Y-direction. Further, the width C of the second deformation restraining portion **518** in the X-direction may be smaller than or the same as the width A of the second coupling portion **32** in the Y-direction.

According to the fifth embodiment, thanks to the first and second deformation restraining portions **517** and **518**, the first and second deformation restraining portions **517** and **518** are locally deformed at the time of the molding process (i.e., a stress is reduced at the first and second deformation restraining portions **517** and **518**), which reduces the deformation of the lead frame **3** as a whole. Therefore, as is the case with the

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first embodiment, it becomes possible to reduce the deformation of the first and second leads **100** and **200** on the side of the external connection ends **101** and **201**.

It is noted that, in the example illustrated in FIG. 8, the first and the second deformation restraining portions **517** and **518** each include a bent portion with one bending position (only one bending to the Y-direction); however, the first deformation restraining portion **517** and/or the second deformation restraining portion **518** each may include a bent portion with more than two bending positions.

All examples and conditional language recited herein are intended for pedagogical purposes to aid the reader in understanding the invention and the concepts contributed by the inventor to furthering the art, and are to be construed as being without limitation to such specifically recited examples and conditions, nor does the organization of such examples in the specification relate to a showing of the superiority and inferiority of the invention. Although the embodiment(s) of the present inventions have been described in detail, it should be understood that the various changes, substitutions, and alterations could be made hereto without departing from the spirit and scope of the invention. Further, all or part of the components of the embodiments described above can be combined.

For example, in the embodiments described above, the first and the second deformation restraining portions **511** and **512**, etc., are provided for the first and second leads **100** and **200**, respectively, as preferred embodiments; however, only one of the first and the second deformation restraining portions **511** and **512**, etc., may be provided. For example, in the example illustrated in FIG. 2, the second deformation restraining portion **512** may be omitted so that only the first deformation restraining portion **511** is provided.

Further, in the embodiments described above, such a configuration in which there are two islands (i.e., the first and second islands **11** and **12**) is assumed; however, the embodiments described above can be applied to a lead frame that includes more than two islands. In this case, lead groups are similarly formed for the respective islands, and intermediate portions like the intermediate portion **40** are formed between the lead groups.

Further, according to the first and second embodiments, the first and the second deformation restraining portions **511** and **512** are formed such that they extend in a direction (i.e., the X-direction) perpendicular to the longitudinal direction (i.e., the Y-direction) of the first and second leads **100** and **200**; however, the first and the second deformation restraining portions **511** and **512** may extend in an inclined direction with respect to the X-direction.

Further, in the first and second embodiments, a plurality of the first deformation restraining portions **511** and a plurality of the second deformation restraining portions **512** may be provided.

The present application is based on Japanese Priority Application No. 2013-156787, filed on Jul. 29, 2013, the entire contents of which are hereby incorporated by reference.

What is claimed is:

1. A lead frame, comprising:

a first island and a second island that are arranged side by side via a predetermined space in a first direction; and
an outer peripheral frame;

a plurality of first leads that extend in a second direction perpendicular to the first direction such that the first leads are arranged side by side in the first direction, wherein each of the first leads has an external connection end at one end in the second direction and a semiconductor element connection end for connecting to a semiconductor element at the other end in the second direction, and wherein the external connection end of each of the first leads before resin for covering the lead frame has been formed;

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a plurality of second leads that extend in the second direction such that the second leads are arranged side by side in the first direction, wherein each of the second leads has an external connection end at one end in the second direction and a semiconductor element connection end for connecting to a semiconductor element at the other end in the second direction, and wherein the external connection end of each of the second leads is a free end separated from the other external connection ends of the second leads before resin for covering the lead frame has been formed;

a first coupling portion that couples the first leads to the outer peripheral frame such that the first coupling portion crosses the first leads; and
a second coupling portion that couples the second leads to the outer peripheral frame such that the second coupling portion crosses the second leads;

an intermediate portion that is formed between the first and second coupling portions in the first direction such that the intermediate portion couples the first coupling portion to the second coupling portion, wherein the intermediate portion extends in the second direction to terminate before the predetermined space between the first and second islands; and

a deformation restraining portion configured to restrain deformations of the first and second leads during a molding process, wherein the deformation restraining portion is formed or provided in at least one of the first leads, the second leads, the first coupling portion and the second coupling portion.

2. The lead frame of claim 1, wherein the deformation restraining portion restrains a deformation mode in which the first leads and the second leads deform in such a direction that a distance between the first leads and the second leads in the first direction on a side of the external connection ends becomes shorter.

3. The lead frame of claim 1, wherein the intermediate portion has one end in the second direction coupled to the outer peripheral frame and another end in the second direction coupled to the first and second coupling portions.

4. The lead frame of claim 1, wherein the deformation restraining portion includes:

a first deformation restraining portion that couples the first leads to the outer peripheral frame such that the first coupling portion crosses the first leads, wherein the first deformation restraining portion is provided such that the first deformation restraining portion is closer to the external connection ends of the first leads with respect to the first coupling portion in the second direction; and

a second deformation restraining portion that couples the second leads to the outer peripheral frame such that the second coupling portion crosses the second leads, wherein the second deformation restraining portion is provided such that the second deformation restraining portion is closer to the external connection ends of the second leads with respect to the second coupling portion in the second direction; and

the intermediate portion further couples the first deformation restraining portion to the second deformation restraining portion.

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the intermediate portion further couples the first deformation restraining portion to the second deformation restraining portion.

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5. An electric power converting device, comprising:
 the lead frame of claim 1 wherein the first coupling portion,
 the second coupling portion, the intermediate portion
 and the deformation restraining portion has been cut
 away;
 a first semiconductor element that is provided on the first
 island and is connected to the semiconductor element
 connection ends of the first leads; and
 a second semiconductor element that is provided on the
 second island and is connected to the semiconductor
 element connection ends of the second leads.
 6. A semiconductor apparatus, comprising:
 the electric power converting device of claim 5; and
 a controller that is connected to the external connection
 ends of the first and second leads.
 7. A method of manufacturing a semiconductor apparatus,
 the method comprising:

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- providing the lead frame of claim 1,
 installing a first semiconductor element and a second semi-
 conductor element on the first and second islands of the
 lead frame, respectively,
 connecting the semiconductor element connection ends of
 the first leads to the first semiconductor element and the
 semiconductor element connection ends of the second
 leads to the second semiconductor element,
 molding a resin on the lead frame such that the external
 connection ends of the first and second leads are exposed
 while pressing the first and second coupling portions
 with a mold; and
 cutting away the first coupling portion, the second coupling
 portion, the intermediate portion and the deformation
 restraining portion.
 8. The lead frame of claim 1, wherein the external connec-
 tion end of each of the first leads is plated and the external
 connection end of each of the second leads is plated.

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